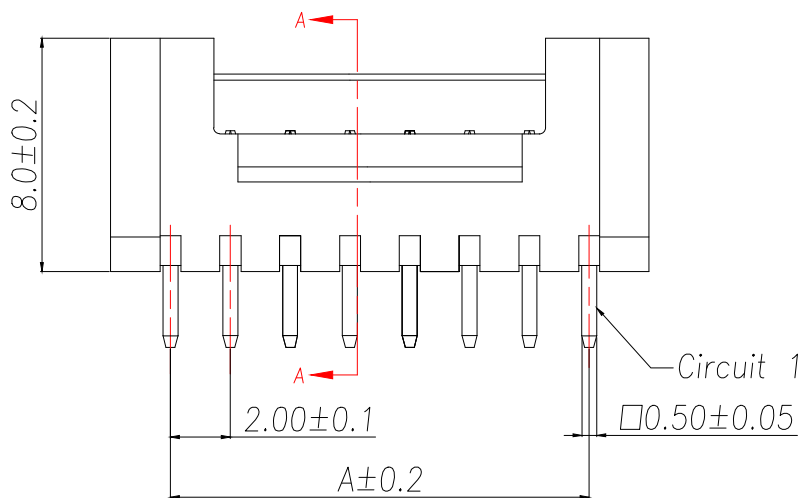
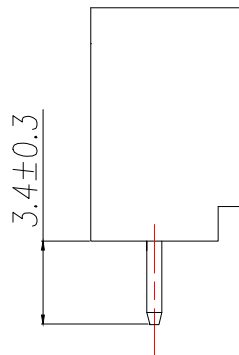
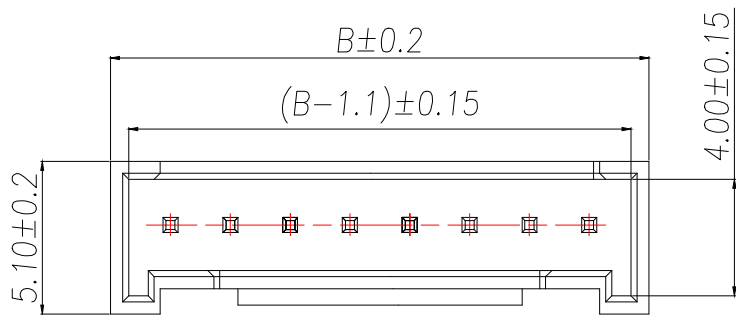
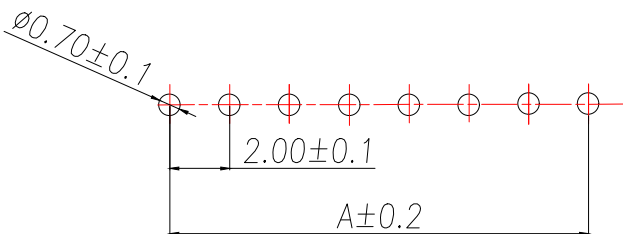


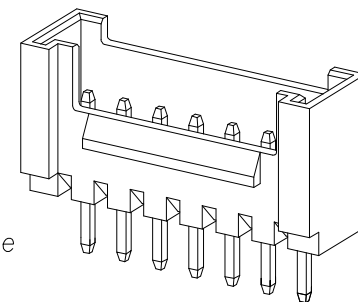
SECTION A-A



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

1. 塑件材料:PA66(UL-94V-0)
2. 接触件:黄铜镀锡
3. 接触电阻: $\leq 10m\Omega$
4. 绝缘电阻: $\geq 100M\Omega$
5. 额定电压:250V AC DC
6. 额定电流:2.0A AC DC
7. 耐压:能承受1000V AC/Minute
8. 工作温度: $-25^{\circ}\sim+85^{\circ}$
9. 可焊性试验:浸锡面积 $\geq 95\%$ 温度 $235\pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
10. 铅和镉等六大有害物质含量要符合环保要求.



Part No	Pin	A	B
HY2.0-2	2	2.00	6.00
HY2.0-3	3	4.00	8.00
HY2.0-4	4	6.00	10.00
HY2.0-5	5	8.00	12.00
HY2.0-6	6	10.00	14.00
HY2.0-7	7	12.00	16.00
HY2.0-8	8	14.00	18.00
HY2.0-9	9	16.00	20.00
HY2.0-10	10	18.00	22.00
HY2.0-11	11	20.00	24.00
HY2.0-12	12	22.00	26.00
HY2.0-13	13	24.00	28.00
HY2.0-14	14	26.00	30.00
HY2.0-15	15	28.00	32.00

2	端子Contact	黄铜	N*1	电镀(锡):整个表面镀底镍 30u"MIN,再镀锡80u"MIN
1	基座Wafer	PA66(UL94V-0)	1	白色
序号	名称	材料	数量	备注
制图 DRAWN	变更内容 DESCRIPTION		日期 DATE	GENERAL TOLERANCE
				.X±0.20 ±2°
				.XX±0.10
				.XXX±0.05

制图 DRAWING	ROSE			料号 PART NO.	RXSY-HY2.0-NPZZ		版本 REV.	A
审核 CHECK	LEO			品名 TITLE	WAFER HY2.0MM 直针		页次 SHEET	1/1
核准 APPROVAL	JOHN			客户料号 CUTM.NO.				
单位 UNITS	MM	比例 SCALE	1:1	深圳市睿新晟业科技有限公司				